Inventor: Kei-Wei Chen

Serial No.: To Be Assigned Filed: Herewith

For: Method Of Forming Barrier Layer With Reduced Resistivity And Improved

Reliability In Copper Damascene Process Attorney Doc. No.: 67,200-1210

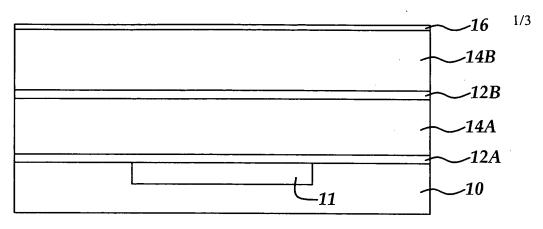


Figure 1A

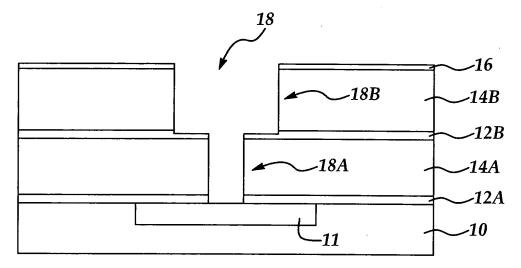


Figure 1B

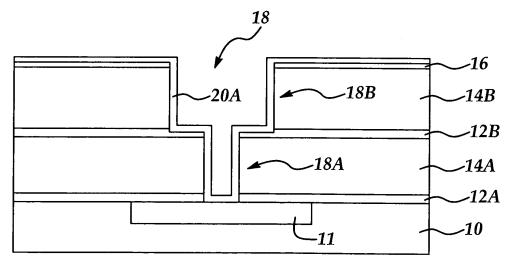


Figure 1C

Inventor: Kei-Wei Chen

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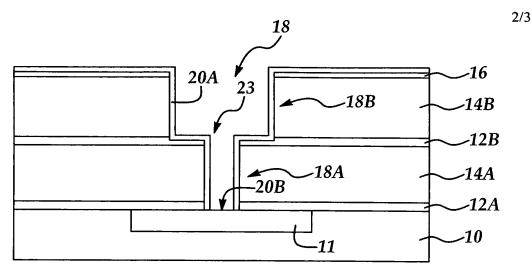


Figure 1D

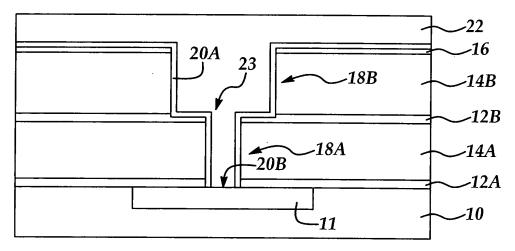


Figure 1E

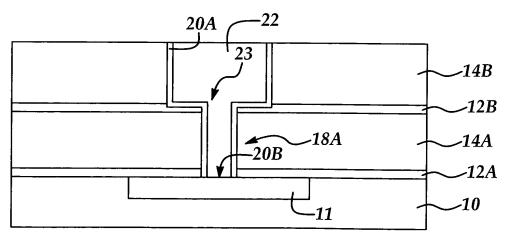


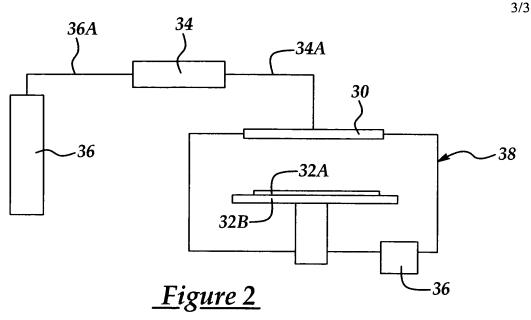
Figure 1F

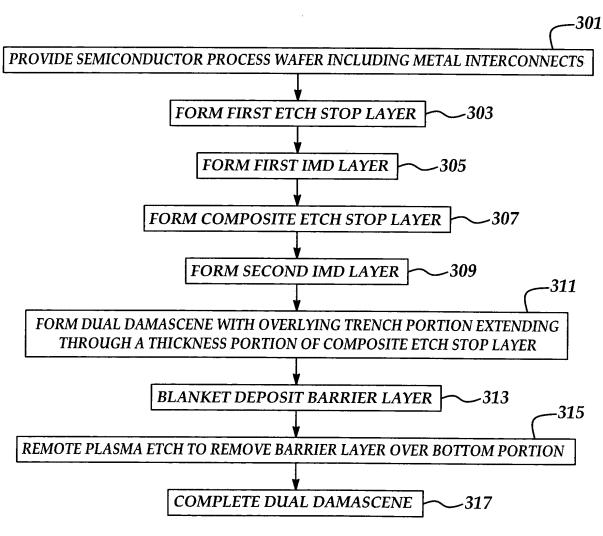
Inventor: Kei-Wei Chen

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<u>Figure 3</u>